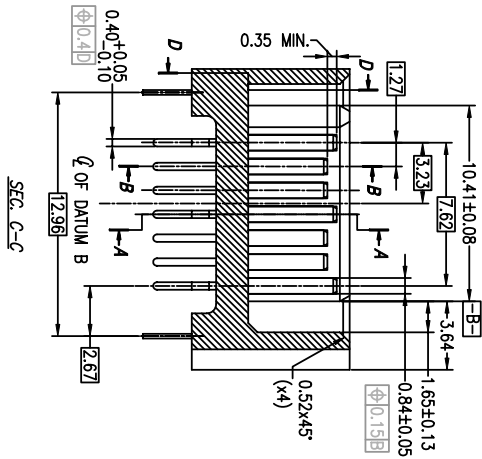
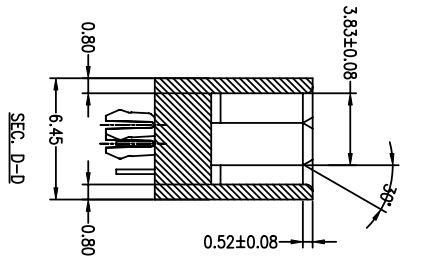
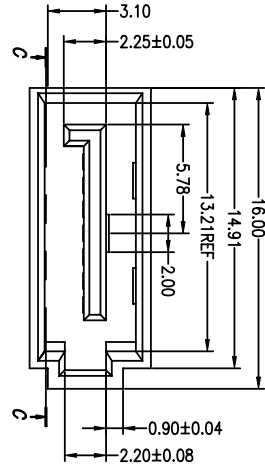
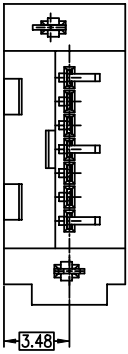
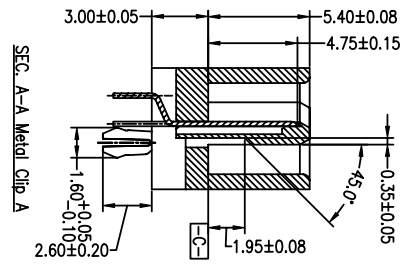
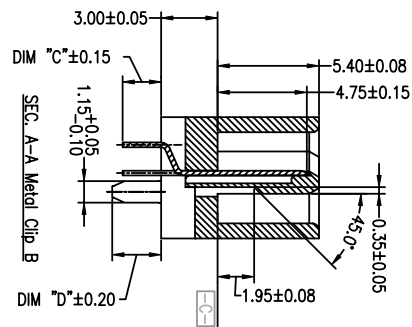
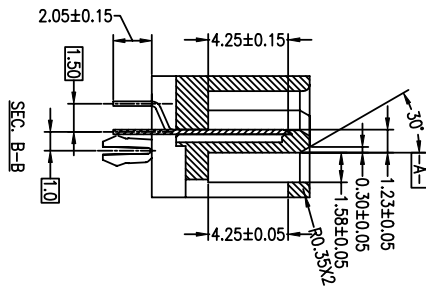


mat'l. code	tolerances unless otherwise specified		CUSTOMER COPY		FCI	title	www.fciconnect.com	
lir	ecn no	dr	date	linear	X ± 0.30	projection	S-ATA SIGNAL PLUG	
A	T05-0213	W.L	09/09/05	.XXX ± 0.20		MM	DIP VERTICAL TYPE ASSY	
B	T08-1033	S.Lin	02/29/08	0' ± 2"		scdle	product family SATA	
		dr	09/09/05				size dng no 10035690	
		engr	09/09/05				code TWIN	
		chr	09/09/05				sheet 1 of	
		appd	09/09/05					
sheet index	revision	sheet	1	2	3	code code		



SUF-FIX	DIM C	DIM D
OTHERS	2.05MM	2.60MM
-XX4XLF	3.05MM	3.40MM



1 | 2

1 | 2

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		title	
lir	ecn no	dr	date	X ± 0.30		www.fciconnect.com	
A	T05-0213	W.L	09/09/05	.XX ± 0.20		S-ATA SIGNAL PLUG	
B	T08-1033	S.Lin	02/29/08	.XXX ± 0.10		DIP VERTICAL TYPE ASSY	
		angles		0° ± 2°			
		dr	09/09/05	MM		product family SATA	
		engr	09/09/05	NA		size dng no 10035690	
		chr	09/09/05			code TWIN	
		appd	09/09/05			sheet 2 of	
sheet	revision	sheet	1	2	3	code code	
index	sheet	index	1	2	3	4	

ACAD

3 |

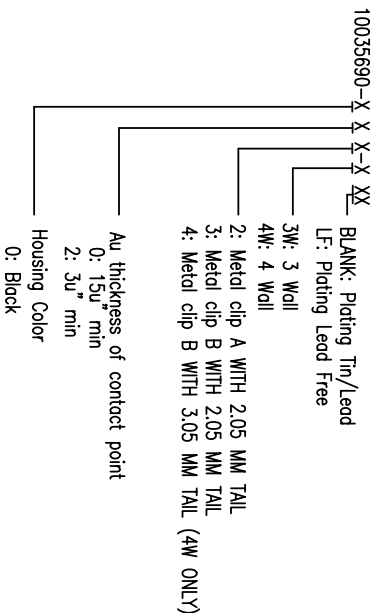
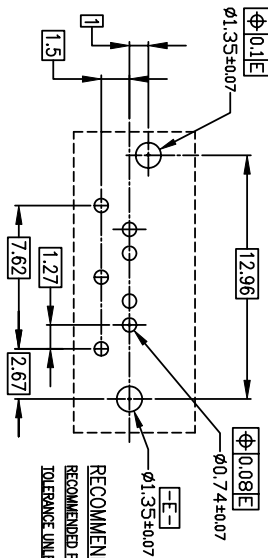
3 |

4

4



1 | 2



3 |

4

- NOTES :
- MATERIAL
    - HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0
    - TERMINAL : COPPER ALLOY
    - HOULD DOWN : COPPER ALLOY
  - FINISH
    - TERMINAL : Au PLATING AT CONTACT POINT  
100u" min Sn-Pb or PURE TIN PLATING AT SOLDER TAIL WITH NICKEL UNDERPLATE
    - HOULD DOWN : 100-200 u" Sn-Pb or PURE TIN PLATING.
  - P/N : 10035690-XXXXLF  
 THE HOUSING WILL WITHSTAND EXPOSURE TO 260 DEGREE C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH 1.6MM MINIMUM THICK CIRCUIT BOARD.
  - Packaging spec: GS-14-840.
  - Product Spec: GS-12-194.

1 | 2

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		FCI		title		code	
ltr	ecn no	dr	date	.X ± 0.30		projection		product family		sheet	
A	T05-0213	W.L	09/09/05	.XX ± 0.20		MM		SATA		TWIN	
B	T08-1033	S.Lin	02/29/08	.XXX ± 0.10		scale		SATA		3 of	
		angles		0° ±2°		NA		10035690			
		dr		Wade Liu 09/09/05							
		engr		Wade Liu 09/09/05							
		chr		Wade Liu 09/09/05							
		appd		Sterling Lin 09/09/05							
sheet	revision										
index	sheet										

3 |

4

ACAD

code code